

4/16/02

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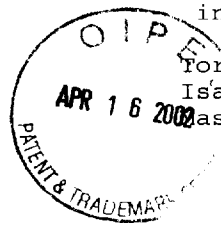
ASA-933

PATENTS ONLY (ref OG 7/28/92)



102062402 MARKS:
Document or copy thereof.

To the Honorable Commission
Please record the attached c



1. Name of Party(ies) conveying an interest:

Toru FUJIOKA, Yoshikuni MATSUNAGA
Is'ao YOSHIDA, Masatoshi MORIKAWA
Masao HOTTA, Tetsuaki ADACHI

2. Name and Address of Party(ies) receiving an interest:

HITACHI, LTD.
6, Kanda Surugadai 4-chome
Chiyoda-ku, Tokyo, JAPAN

HITACHI TOHBU SEMICONDUCTOR, LTD.
1-1, Nishiyokote-machi
Takasaki-shi, Gunma, JAPAN

3. Description of the interest conveyed: Assignment

4. Application number(s) or patent number(s).

Additional sheet attached? ___ Yes XXX No

If this document is being filed together with a new application,
the execution date of the application is: _____
DATE

A. Patent Application No. (s)

09/657,237

B. Patent No. (s)

5. Name and address of party to whom correspondence concerning document should be mailed:

John R. Mattingly
Mattingly, Stanger & Malur, P.C.
1800 Diagonal Road, Suite 370
Alexandria, Virginia 22314

6. Number of applications and patents involved: One

7. Amount of fee enclosed or authorized to be charged: \$40.00

8. The Commissioner is hereby authorized to charge Deposit Account No. 50-1417 if no check is attached.

DO NOT USE THIS SPACE

9. Execution date of attached document: August 9, 18 and 23, 2000

10. To the best of my knowledge and belief, I declare under penalty of perjury under the laws of the United States of America that the foregoing information is true and correct and that any attached copy is a true copy of the original document.

John R. Mattingly
Name of Person Signing

John R. Mattingly
Signature

April 16, 2002
Date

Total number of pages being submitted: 2

04/19/2002 LMUELLER 00000233 09657237
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PATENT
REEL: 012800 FRAME: 0684

ASSIGNMENT

(讓渡証)

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to Toru FUJIOKA, Yoshikuni MATSUNAGA, Isao YOSHIDA, Masatoshi MORIKAWA, Masao HOTTA, and Tetsuaki ADACHI, citizens of Japan by HITACHI, LTD., and Hitachi Tohbu Semiconductor, Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 1-1, Nishiyokote-machi, Takasaki-shi, Gunma, Japan, respectively, receipt of which is hereby acknowledged, we, the said Toru FUJIOKA, Yoshikuni MATSUNAGA, Isao YOSHIDA, Masatoshi MORIKAWA, Masao HOTTA, and Tetsuaki ADACHI, do hereby sell and assign to said HITACHI, LTD., and Hitachi Tohbu Semiconductor, Ltd.,

their successors and assigns, all our right, title and interest, in and for the United States of America, in and to HIGH FREQUENCY POWER AMPLIFYING MODULE AND WIRELESS COMMUNICATION APPARATUS invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi Tohbu Semiconductor, Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi Tohbu Semiconductor, Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Toru FUJIOKA</u> Toru FUJIOKA	<u>9/August/2000</u>
2) <u>Yoshikuni Matsunaga</u> Yoshikuni MATSUNAGA	<u>9/August/2000</u>
3) <u>Isao Yoshida</u> Isao YOSHIDA	<u>9/August/2000</u>
4) <u>Masatoshi Morikawa</u> Masatoshi MORIKAWA	<u>9/August/2000</u>
5) <u>Masao Hotta</u> Masao HOTTA	<u>18/Aug/2000</u>
6) <u>Tetsuaki Adachi</u> Tetsuaki ADACHI	<u>23/Aug/2000</u>
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____